

YDS-J1MF-IMX258 V1.0

13MP Sony IMX258 MIPI Interface Fixed Focus Camera Module



Front View



Back View

Specifications

Camera Module No.	YDS-J1MF-IMX258 V1.0		
Resolution	13MP		
Image Sensor	IMX258		
Sensor Type	1/3.06"		
Pixel Size	1.12 um x 1.12 um		
EFL	3.81 mm		
F.NO	2.20		
Pixel	4224 x 3136		
View Angle	74.4°(DFOV) 62.7°(HFOV) 48.7°(VFOV)		
Lens Dimensions	8.50 x 8.50 x 5.45 mm		
Module Size	20.85 x 8.50 mm		
Module Type	Fixed Focus		
Interface	MIPI		
Auto Focus VCM Driver IC	None		
Lens Model	YDS-LENS-50013A1		
Lens Type	650nm IR Cut		
Operating Temperature	-20°C to +70°C		
Mating Connector	BBR43-30KB533		

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Top View

Side View





Bottom View

Mating Connector

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Parameters: 3 1. Sensor specification: 3 Image Sensor: IMX258 Pixel: 1.12um×1.12um Lens Type: 1/3.06 Important Voltage Description: DVDD1.2V (external power supply); A	12 ASHOLICOWN 13 MCN 14 NC 15 MCP 16 GND 17 MDON 20 GND 21 MDIN 23 MD1N 24 AVDD2.8V 26 AGND 27 MD2N 28 MD3N 30 MD3P	
1: 2 、 Lens specification: FOV: 74.4° F/NO.: 2.2 TV distortion: <1.5%	TOP VIEW 50±0.10 8.50±0.10 8.50±0.10 6.00±0.10 6.00±0.10 6.00±0.10	
Designed By Checked By		5.45±0.20 4.82±0.20
Kevin Model Name: J1MF-IMX258 V1.0 Projection Type: unit: Material: Aouly_Yan Image: Scale: Sheet: Version: D Third Angle 1 of 1 Version:	BOTTOM VIEW NOTE: 1.The device slave address:0x34; 2.Driver IC and its I2C Address: NW9763. 0x18h.	D E Version Mark Information ▶ First Version ▲ ●
	··	Date 2019-03-13 1

SONY

[Product Brief]

Ver.1.0

IMX258

Diagonal 5.867 mm (Type 1/3.06) 13Mega-Pixel CMOS Image Sensor with Square Pixel for Color Cameras

Description

IMX258 is a diagonal 5.867mm (Type 1/3.06) 13 Mega-pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RS[™] technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spatially multiplexed exposure technology, high dynamic range still pictures and movies are achievable. It

equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.2 V and 1.8 V for input/output interface and achieves low power consumption.

In addition, this product is designed for use in cellular phone and tablet pc. When using this for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and tablet pc. Consult your Sony sales representative if you have any questions.

Functions and Features

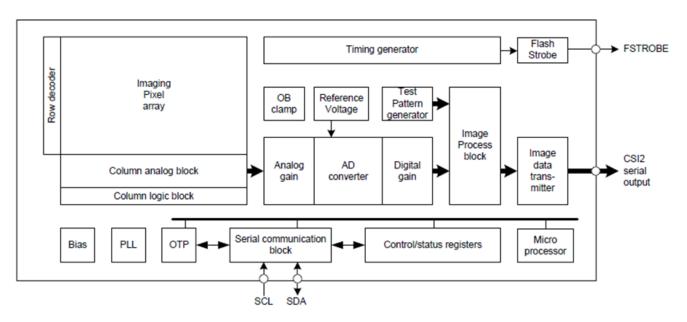
- Back-illuminated and stacked CMOS image sensor Exmor RSTM
- Phase Detection pixel data output for Phase Detection Auto Focus
- High Dynamic Range (HDR) mode with raw data output.
- High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR). 4K2K @30fps (Normal / HDR) 1080p @60fps (Normal)
- Output video format of RAW10/8.
- Pixel binning readout and V sub-sampling function.
- Independent flipping and mirroring.
- CSI-2 serial data output (MIPI 2lane/4lane, Max. 1.3Gbps/lane, D-PHY spec. ver. 1.1 compliant)
- ◆ 2-wire serial communication.
- Two PLLs for independent clock generation for pixel control and data output interface.
- Dynamic Defect Pixel Correction.
- Fast mode transition. (on the fly)
- Dual sensor synchronization operation.
- 4K bit of OTP ROM for users.
- Built-in temperature sensor.

Device Structure

- CMOS image sensor
- Image size :
- Total number of pixels :
- Number of effective pixels :
- Number of active pixels :
- Chip size :
- Unit cell size :
- Substrate material :

Diagonal 5.867 mm (Type 1/3.06) 4224 (H) × 3192 (V) approx. 13.48 M pixels 4224 (H) × 3144 (V) approx. 13.28 M pixels 4208 (H) × 3120 (V) approx. 13.13 M pixels 5.990 mm (H) × 3.908 mm (V) 1.12 μ m (H) × 1.12 μ m (V) Silicon

System block diagram



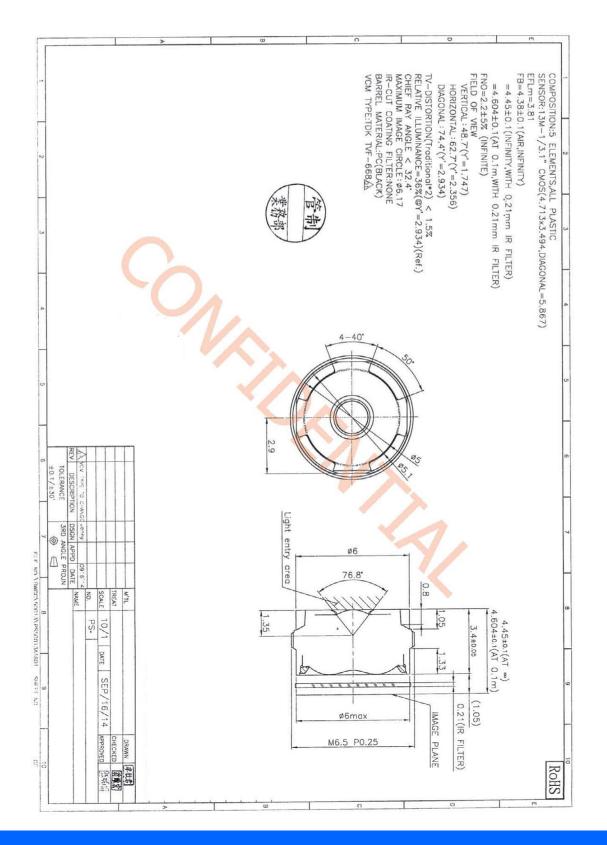


* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R[™] which changed fundamental structure of Exmor [™] pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.

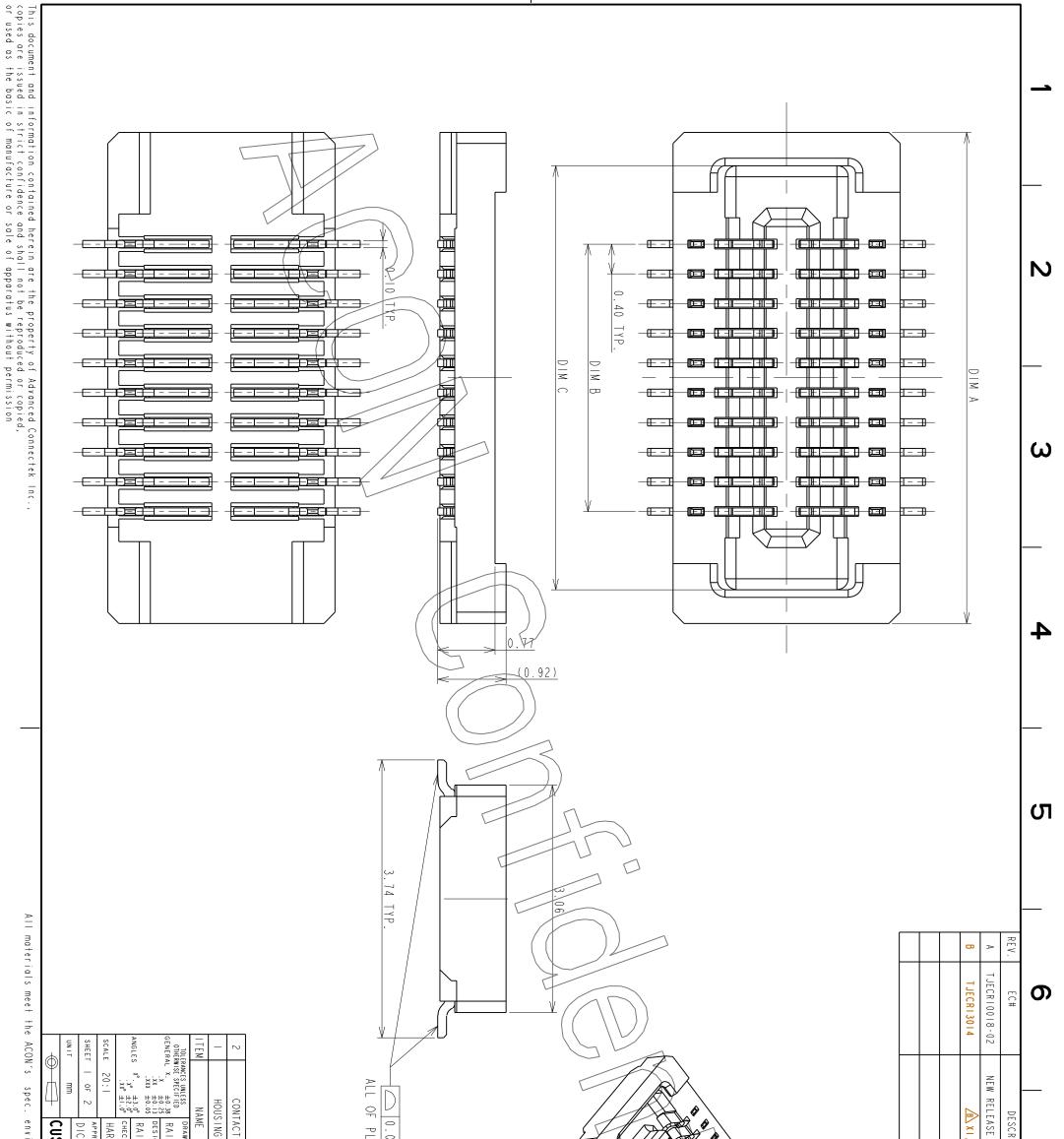


YDS-LENS-50013A1

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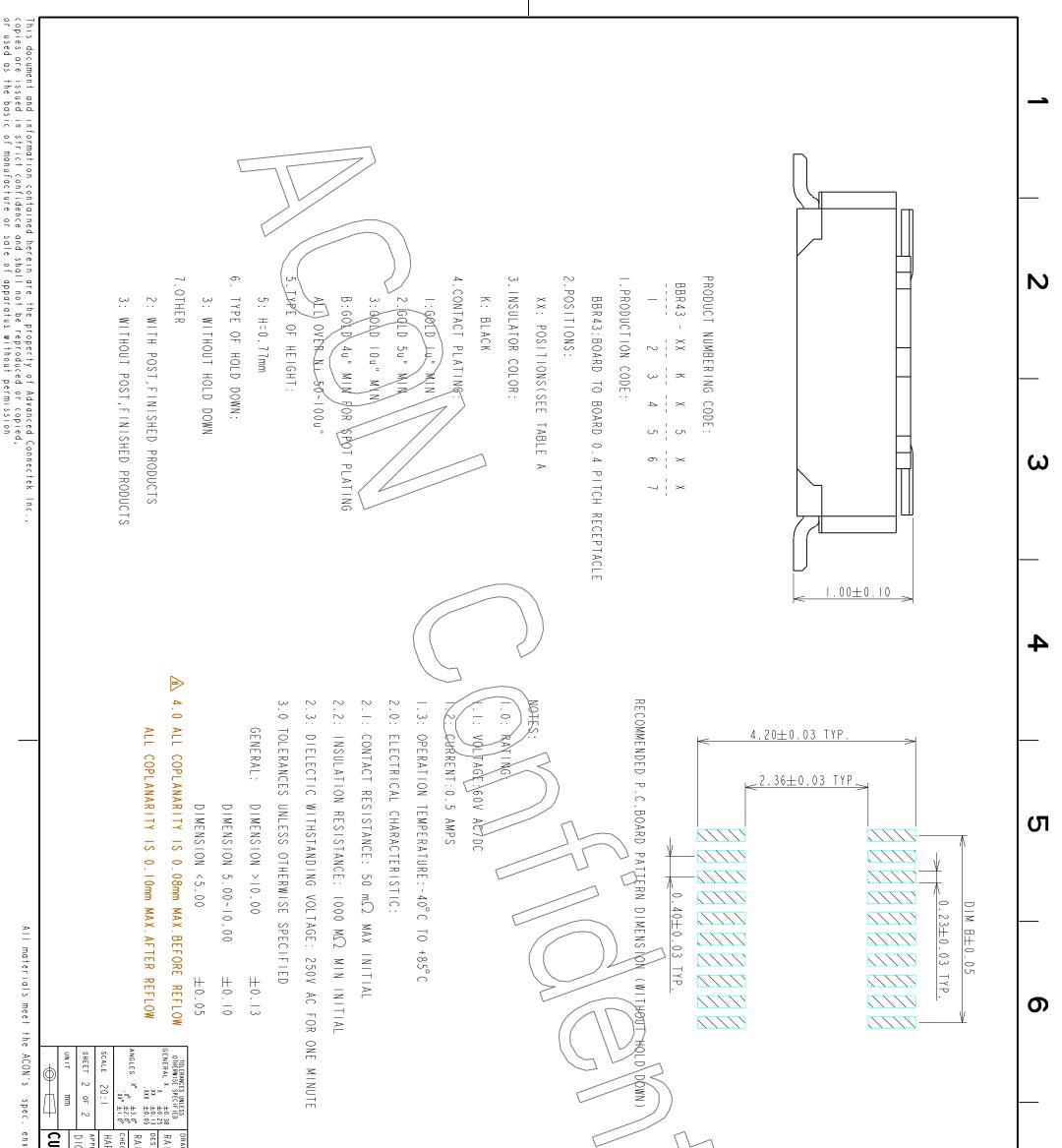


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Camera Module Pinout Definition Reference Chart

OmniVision Sony Samsung On-Semi Ap	tina Himax GalaxyCore PixArt SmartSens Sensors
Pin Signal	Description
DGND GND	ground for digital circuit
AGND	ground for analog circuit
PCLK DCK	DVP PCLK output
XCLR PWDN XSHUTDOWN STANDBY	power down active high with internal pull-down resistor
MCLK XVCLK XCLK INCK	system input clock
RESET RST	reset active low with internal pull-up resistor
NC NULL	no connect
SDA SIO_D SIOD	SCCB data
SCL SIO_C SIOC	SCCB input clock
VSYNC XVS FSYNC	DVP VSYNC output
HREF XHS	DVP HREF output
DOVDD	power for I/O circuit
AFVDD	power for VCM circuit
AVDD	power for analog circuit
DVDD	power for digital circuit
STROBE FSTROBE	strobe output
FSIN	synchronize the VSYNC signal from the other sensor
SID	SCCB last bit ID input
ILPWM	mechanical shutter output indicator
FREX	frame exposure / mechanical shutter
GPIO	general purpose inputs
SLASEL	I2C slave address select
AFEN	CEN chip enable active high on VCM driver IC
MIPI Interface	
MDN0 DN0 MD0N DATA_N DM01N	MIPI 1st data lane negative output
MDP0 DP0 MD0P DATA P DM01P	MIPI 1st data lane positive output
MDN1 DN1 MD1N DATA2 N DMO2N	MIPI 2nd data lane negative output
MDP1 DP1 MD1P DATA2 P DM02P	MIPI 2nd data lane positive output
MDN2 DN2 MD2N DATA3 N DMO3N	MIPI 3rd data lane negative output
MDP2 DP2 MD2P DATA3 P DMO3P	MIPI 3rd data lane positive output
MDN3 DN3 MD3N DATA4 N DMO4N	MIPI 4th data lane negative output
MDP3 DP3 MD3P DATA4_P DMO4P	MIPI 4th data lane positive output
MCN CLKN CLK_N DCKN	MIPI clock negative output
MCP CLKP MCP CLK_P DCKN	MIPI clock positive output
DVP Parallel Interface	
D0 D00 Y0	DVP data output port 0
D1 D01 Y1	DVP data output port 1
D2 DO2 Y2	DVP data output port 2
D3 D03 Y3	DVP data output port 3
D4 D04 Y4 D5 D05 Y5	DVP data output port 4
	DVP data output port 5
D6 D06 Y6	DVP data output port 6
D7 D07 Y7	DVP data output port 7
D8 D08 Y8	DVP data output port 8
D9 D09 Y9	DVP data output port 9
D10 D010 Y10	DVP data output port 10
D11 D011 Y11	DVP data output port 11

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Cameras Applications

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Camera Reliability Test

	Reliability Inspect	ion Item	Testing Mathed	Acceptance Criteria	
Category		Item	Testing Method	Acceptance Criteria	
	Storage	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation	
Environmental	Temperature	Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation	
	Operation	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation	
	Temperature	Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation	
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation	
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation	
	Drop Test	Without Package 60cm	10 Times on Wood Floor	Electrically Functional	
	(Free Falling)	With Package 60cm	10 Times on Wood Floor	Electrically Functional	
		50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional	
Physical	Vibration Test	50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional	
Physical		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional	
	Cable Tensile Strength Test Cable Tensile Cycling in 24 Hours		Tensile Testing Machine	Electrically Functional	
		Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional	
	ESD Test	Air Discharge 4 KV	ESD Testing Machine	Electrically Functional	
Electrical	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional	
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional	



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Camera Inspection Standard

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Inspection Item			Inspection Method	Standard of Inspection
Category		Item	Inspection Method	Standard of Inspection
		Color	The Naked Eye	Major Difference is Not Allowed.
	FPC/ PCB	Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.
Appearance		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed
		Gap	The Naked Eye	Meet the Height Standard
	noidei	Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed
		Scratch	The Naked Eye	No Effect On Resolution Standard
	Long	Contamination	The Naked Eye	No Effect On Resolution Standard
	Lens	Oil Film	The Naked Eye	No Effect On Resolution Standard
		Cover Tape	The Naked Eye	No Issue On Appearance.
		No Communication	Test Board	Not Allowed
		Bright Pixel	Black Board	Not Allowed In the Image Center
		Dark Pixel	White board	Not Allowed In the Image Center
		Blurry	The Naked Eye	Not Allowed
		No Image	The Naked Eye	Not Allowed
	Image	Vertical Line	The Naked Eye	Not Allowed
		Horizontal Line	The Naked Eye	Not Allowed
Function		Light Leakage	The Naked Eye	Not Allowed
		Blinking Image	The Naked Eye	Not Allowed
		Bruise	Inspection Jig	Not Allowed
		Resolution	Chart	Follows Outgoing Inspection Chart Standard
		Color	The Naked Eye	No Issue
		Noise	The Naked Eye	Not Allowed
		Corner Dark	The Naked Eye	Less Than 100px By 100px
		Color Resolution	The Naked Eye	No Issue
		Height	The Naked Eye	Follows Approval Data Sheet
Dimen	sion	Width	The Naked Eye	Follows Approval Data Sheet
Dimen	191011	Length	The Naked Eye	Follows Approval Data Sheet
		Overall	The Naked Eye	Follows Approval Data Sheet

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YDSCAM Package Solutions

YDS Camera Module



Tray with Grid and Space

Complete with Lens Protection Film



Place Cameras on the Tray





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YDSCAM Package Solutions

Full Tray of Cameras

DS



Place Tray into Anti-Static Bag

Cover Tray with Lid



Vacuum the Anti-Static Bag



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YDSCAM Package Solutions

Sealed Vacuum Anti-Static Bag with Labels

1. Model and Description 2. Quantity 3. Manufacturing Date Code 4. Caution



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YDSCAM Package Solutions

Place Foam Sheets Between Tray Bags



Place Foam Sheets and Trays into Box



Seal the Carbon Box



Foam Sheets are Larger Than Trays



Foam Sheets are Tightly Fitting in Box



Label the Carbon Shipping Box



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YDSCAM Package Solutions

USB Camera Module







Place Camera Sample into Anti-Static Bag

Place USB Cameras into Tray







Seal the Tray with Anti-Static Bag



Label the Carbon Shipping Box



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Complete with Lens Protection Film



YDSCAM Package Solutions

Place Camera Sample into Anti-Static Bag





Label the Sample Bags

Place Connectors into Anti-Static Bag



Place Connectors into Reel



Place Samples into the Carbon Box





Place Connectors into the Carbon Box



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YDS

Company YDSCAM

YingDeShun Co. Ltd. (YDS) was established in 2017, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. YDS is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

YDS provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. YDS specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



Limited Warranty

YDS provides the following limited warranty if you purchased the Product(s) directly from YDS company or from YDS's website <u>www.YDSCAM.com</u>. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. YDS guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, YDS will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of YDS is solely limited to repair and/or replacement on the terms set forth above. YDS is not reliable or responsible for any subsequential events.



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YDS Strength

Y

Powerful Factory



Professional Service



Promised Delivery



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